

PATENT Attorney Docket No. ASC-012DV

### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S):

Lee et al.

SERIAL NO.:

10/788,741

**GROUP NO.:** 

2813

FILING DATE:

February 27, 2004

**EXAMINER:** 

Craig Thompson

TITLE:

STRUCTURES WITH PLANAR STRAINED LAYERS

## CERTIFICATE OF FIRST CLASS MAILING UNDER 37 C.F.R. 1.8

I hereby certify that this correspondence, and any document(s) referred to as enclosed herein, is/are being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 23<sup>rd</sup> day of March, 2005.

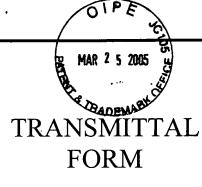
Wendy L. Martin

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

#### Submitted herewith are:

- 1. Transmittal Form (1 page);
- 2. Supplemental Information Disclosure Statement (2 pages);
- 3. PTO Form 1449 (4 pages);
- 4. Copies of cited references (C75 C95); and
- 5. Return receipt postcard



Application Serial Number	10/788,741
Filing Date	February 27, 2004
First Named Inventor	Lee
Group Art Unit	2813
Examiner Name	Craig Thompson
Attorney Docket No.	ASC-012DV
Patent No.	Not applicable
Issue Date	Not applicable

			Patent No.			Not applicable				
			Issue Date		Not applicable					
		EN	CLOSURES (c	heck all that apply)						
	Fee Transmittal Form		Copy of Notic Parts of Appli	e to File Missing cation		Notice of Appeal to Board of Patent Appeals and Interferences				
	☐ Check Attached☐ Copy of Fee Transmittal Form		Formal Drawi	ng(s)	ַ	Appeal Brief (in triplicate)				
	Amendment/Response		Request For C Examination (			Status Inquiry				
	Preliminary After Final		Transmittal			Return Receipt Postcard				
	☐ Affidavits/declaration(s) ☐ Letter to Official ☐ Draftsperson		Power of Atto (Revocation o	rney f Prior Powers)	Σ	Certificate of First Class Mailing under 37 C.F.R. 1.8				
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	Petition for Extension of Time			aration and Power rutility or Design ation		Additional Enclosure(s) (please identify below)				
$\boxtimes$	Supplemental Information Disclosure Statement		Small Entity Statement							
	<ul><li>✓ Form PTO-1449</li><li>✓ Copies of IDS</li><li>Citations (C75 – C95)</li></ul>	CD(s) for large table or computer program								
	Certified Copy of Priority Document(s)		Amendment A	fter Allowance						
	Sequence Listing submission Paper Copy/CD Computer Readable Copy Statement verifying identity of above		Request for Certificate of Correction Certificate of Correction (in duplicate)							
COR	RESPONDENCE ADDRESS			SIGNATURE BL	OC.					
Direc	Goodwin Exchange Boston, M Tel. No.: Fax No.:	Iministrato Procter LL Place AA 02109 (617) 570- (617) 523- No. 0514	-1000 -1231	Date: March 23, 200 Reg. No. 44,381 Tel. No.: (617) 570 Fax No.: (617) 523						

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Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

#### SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with the provisions of 37 C.F.R. 1.97 and 1.98, Applicants hereby make of record the patents and publications listed on the accompanying Form PTO-1449, and other information contained herein, for consideration by the Examiner in connection with the examination of the above-identified patent application. In accordance with the U.S. Patent Office's partial waiver of the requirement under 37 C.F.R. 1.98(a)(2)(i), only copies of the non-patent publications are enclosed.

#### **REMARKS**

In accordance with the provisions of 37 C.F.R. 1.97, this statement is being filed (CHECK ONE):

(1)	within three (3) months of the <b>filing date</b> of a national application other than a continued prosecution application under 37 C.F.R. 1.53(d), or within three (3) months of the <b>date of entry of the national stage</b> as set forth in 37 C.F.R. 1.491 in an international application, or before the mailing of the <b>first Office action</b> on the merits, or before the mailing of a <b>first Office action</b> after the filing of a request for continued examination under 37 C.F.R. 1.114; or
(2)	after the period defined in (1) but before the mailing date of a final action or a notice of allowance under 37 C.F.R. 1.311, and
	the requisite Statement is below, <b>OR</b>
	the requisite fee under 37 C.F.R. 1.17(p), namely \$180.00, is included herein, or

Information Disclosure Statement Serial No.10/788,741 Page 2 of 2 after the mailing date of a final action or notice of allowance but before the payment of (3) the issue fee, AND the requisite Statement is below, AND the requisite petition fee under 37 C.F.R. 1.17(p), namely \$180.00 is included herein. It is respectfully requested that each of the patents and publications listed on the attached Form PTO-1449, and other information contained herein, be made of record in this application. **STATEMENT** As required under 37 C.F.R. 1.97(e), Applicant(s), through the undersigned, hereby state either that check the appropriate space only if either (2) or (3) is checked on the previous page and the Statement is required]: П Each item of information contained in the Information Disclosure Statement was 1. first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement; or 2. No item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing this Statement after making reasonable inquiry, no item of information contained in the Information Disclosure Statement was known to any individual designated in 37 C.F.R. 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.

Respectfully submitted,

Date: March 23, 2005 Reg. No. 44,381

1109.110.11,501

Tel. No.: (617) 570-1806 Fax No.: (617) 523-1231

VER 12/00

Natasha C. Us

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Boston, Massachusetts 02109

Customer No. 051414



**FORM PTO - 1449** 

# SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.: ASC-012DV

APPLICANT(S): Lee et al.

SERIAL NO.: 10/788,741

FILING DATE: February 27, 2004

GROUP: 2813

EXAM. INIT.	A75 2002/0063292 05/30/20		DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
			05/30/2002	Armstrong et al.				
	A76	2002/0190284	12/19/2002	Murthy et al.				
<u>.</u>	A77	2004/0007724	01/15/2004	Murthy et al.				
	A78	2004/0014276	01/22/2004	Murthy et al.				
	A79	2004/0070035	04/15/2004	Murthy et al.				
-	A80	2004/0084735	05/06/2004	Murthy et al.				
	A81	2004/0119101	06/24/2004	Schrom et al.				
	A82	2004/0142545	07/22/2004	Ngo et al.				
	A83	2004/0173815	09/09/2004	Yeo et al.				
	A84	5,089,872	02/18/1992	Ozturk et al.				
	A85	5,242,847	09/07/1993	Ozturk et al.				
	A86	6,228,694	05/08/2001	Doyle et al.				
-	A87	6,235,568	05/22/2001	Murthy et al.				
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	A89	6,326,664	12/04/2001	Chau et al.				
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	A95	6,743,684	06/01/2004	Liu				

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~	Gannavaram, et al., "Low Temperature (≤800°C) Recessed Junction Selective Silicon-Germanium Source/Drain Technology for sub-70 nm CMOS," <u>IEEE International Electron Device Meeting Technology</u> , (2000), pp. 437-440.												
·.	C76	Ge et al., "Process- International Elect							ngineering	ing," <u>IEEE</u>			
	C77 Ghani et al., "A 90nm High Volume Manufacturing Logic Technology Featuring Novel 45nm G. Strained Silicon CMOS Transistors," <u>IEEE International Electron Devices Meeting Technical Dig</u> 978-980.												
_	C78	Hamada et al., "A Electron Devices,"						d MOS De	vices," <u>IEF</u>	E Tran	sactions on		
C79 Huang <i>et al.</i> , "Isolation Process Dependence of Channel Mobility in Thin-Film SOI Device Device Letters, Vol. 17, No. 6 (June 1996), pp. 291-293.								es," <u>IE</u> l	EE_Electron				
	C80	Huang et al., "LOO Devices, Vol. 44, 1					m SOI Dev	/ices," <u>IEE</u>	E Transact	ions on	Electron		
	C81	Huang, et al., "Rec Transistors with Rapp. 448-450.											
	C82	lida et al., "Therm mobility," Solid-Si						or bonded v	vafer and e	ffects o	n electron		
		oo, <u>so s</u>			UI. 43 (17.	<i>99)</i> , pp. 11	17-1120.						

#### ATTORNEY DOCKET NO.: ASC-012DV **FORM PTO – 1449** SUPPLEMENTAL INFORMATION APPLICANT(S): Lee et al. DISCLOSURE STATEMENT SERIAL NO.: 10/788,741 FILING DATE: February 27, 2004 GROUP: 2813 U.S. PATENT DOCUMENTS DATE **CLASS** SUB FILING DATE IF DOCUMENT NAME EXAM. CLASS APPROPRIATE INIT. NUMBER FOREIGN PATENT DOCUMENTS ENGLISH **COUNTRY** CLASS SUB FILING ABSTRACT DATE EXAM. DOCUMENT INIT. CODE **CLASS** DATE ONLY LANG NUMBER (Y/N) OTHER ART, JOURNAL ARTICLES, ETC. OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication) EXAM. INIT. Ito et al., "Mechanical Stress Effect on Etch-Stop Nitride and its Impact on Deep Submicron Transistor C83 Design," IEEE International Electron Devices Meeting Technical Digest, (2000), pp. 247-250. C84 Lochtefeld et al., "Investigating the Relationship Between Electron Mobility and Velocity in Deeply Scaled NMOS via Mechanical Stress," IEEE Electron Device Letters, Vol. 22, No. 12 (2001), pp. 591-593. Ootsuka et al., "A Highly Dense, High-Performance 130nm node CMOS Technology for Large Scale System-C85 on-a-Chip Applications," IEEE International Electron Devices Meeting Technical Digest, (2000), pp. 575-578. Ota et al., "Novel Locally Strained Channel Technique for High Performance 55nm CMOS," IEEE C86 International Electron Devices Meeting Technical Digest, (2002), pp. 27-30. Öztürk, et al., "Advanced Si<sub>1-x</sub>Ge<sub>x</sub> Source/Drain and Contact Technologies for Sub-70 nm CMOS," <u>IEEE</u> C87 International Electron Device Meeting Technical Digest, (2002), pp. 375-378. Öztürk, et al., "Low Resistivity Nickel Germanosilicide Contacts to Ultra-Shallow Si<sub>1-x</sub>Ge<sub>x</sub> Source/Drain C88 Junctions for Nanoscale CMOS," IEEE International Electron Device Meeting Technical Digest (2003), pp. 497-500. C89 Öztürk, et al., "Selective Silicon-Gremanium Source/Drain Technology for Nanoscale CMOS," Mat. Res. Soc. Symp. Proc., Vol. 717, (2002), pp. C4.1.1-C4.1.12. Öztürk, et al., "Ultra-Shallow Source/Drain Junctions for Nanoscale CMOS Using Selective Silicon-Germanium Technology," Extended Abstracts of International Workshop on Junction Technology, (2001), pp. 77-82. DATE CONSIDERED **EXAMINER**

FORM	PTO –	1449			ATTORN	EY DOCK	KET NO.:	ASC-012	2DV		
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT				APPLICANT(S): Lee et al.							
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	C92	Thompson <i>et al.</i> , '25, No. 4 (April 2	-		Featuring Str	ained-Silic	on," <u>IEEE</u>	Electron D	evice L	etters, Vol.	
	C93 Thompson <i>et al.</i> , "A 90 nm Logic Technology Featuring 50nm Strained-Silicon Channel Transisto of Cu <i>Interconnects</i> , Low k ILD, and Ium <sup>2</sup> SRAM Cell," <u>IEEE International Electron Devices Meditechnical Digest</u> , (2002), pp. 61-64.								ors, 7 layers eeting		
C94 Tiwari et al., "Hole Mobility Improvement in Silicon-on-Insulator and Bulk Silicon Trans Strain," IEEE International Electron Devices Meeting Technical Digest, (1997), pp. 939-9								sing Local			
	C95	Uchino, <i>et al.</i> , "A Raised Source/Drain Technology Using In-situ P-doped SiGe and B-doped Si for 0.1-µm CMOS ULSIs," <u>IEEE International Electron Device Meeting Technical Digest</u> , (1997), pp. 479-482.									
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